



Material Content Data Sheet



Halogen-Free

Sales Product Name	IPD65R660CFD	Issued	01. April 2021
MA#	MA001180288		
Package	PG-TO252-3-313	Weight*	319.04 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.294	1.03	1.03	10325	10325
leadframe	inorganic material	phosphorus	7723-14-0	0.044	0.01		139	
	non noble metal	iron	7439-89-6	0.147	0.05		462	
	non noble metal	copper	7440-50-8	147.096	46.11	46.17	461061	461662
wire	non noble metal	aluminium	7429-90-5	0.661	0.21	0.21	2071	2071
encapsulation	inorganic material	zinc oxide	1314-13-2	1.404	0.44		4402	
	miscellaneous	miscellaneous	-	7.022	2.20		22008	
	plastics	epoxy resin	-	21.065	6.60		66025	
	inorganic material	silicon dioxide	60676-86-0	110.940	34.77	44.01	347734	440169
lead finish	non noble metal	tin	7440-31-5	3.740	1.17	1.17	11723	11723
plating	inorganic material	phosphorus	7723-14-0	0.003			11	
	non noble metal	nickel	7440-02-0	1.421	0.45	0.45	4453	4464
solder	non noble metal	tin	7440-31-5	0.060	0.02		188	
	noble metal	silver	7440-22-4	0.075	0.02		235	
	non noble metal	lead	7439-92-1	2.863	0.90	0.94	8975	9398
heatspreader	inorganic material	phosphorus	7723-14-0	0.006			18	
	non noble metal	iron	7439-89-6	0.019	0.01		60	
	non noble metal	copper	7440-50-8	19.177	6.01	6.02	60110	60188
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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